ON Semiconductor

Is Now



To learn more about onsemi™, please visit our website at www.onsemi.com

onsemi and ONSEMI. and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries. onsemi owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of onsemi product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. onsemi reserves the right to make changes at any time to any products or information herein is provided "as-is" and onsemi makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using onsemi products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by onsemi. "Typical" parameters which may be provided in onsemi data sheets and/ or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. onsemi does not convey any license under any of its intellectual property rights nor the rights of others. onsemi products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use onsemi products for any such unintended or unauthorized application,



ON Semiconductor®

FDS6298

30V N-Channel Fast Switching PowerTrench® MOSFET

General Description

This N-Channel MOSFET has been designed specifically to improve the overall efficiency of DC/DC converters using either synchronous or conventional switching PWM controllers. It has been optimized for low gate charge, low $R_{\text{DS(ON)}}$ and fast switching speed.

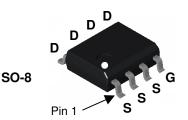
Applications

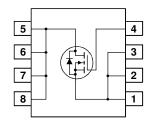
- Control Switch for DC-DC Buck converters
- Notebook Vcore
- Telecom / Networking Point of Load



Features

- 13 A, 30 V. $R_{DS(ON)} = 9 \text{ m}\Omega$ @ $V_{GS} = 10 \text{ V}$ $R_{DS(ON)} = 12 \text{ m}\Omega$ @ $V_{GS} = 4.5 \text{ V}$
- Low gate charge (10nC @ V_{GS}=5V)
- Very low Miller Charge (3nC)
- Low Rg (1 Ohm)
- ROHS Compliant





Absolute Maximum Ratings T_A=25°C unless otherwise noted

Symbol	Parameter		Ratings	Units	
V _{DSS}	Drain-Source Voltage		30	V	
V _{GSS}	Gate-Source Voltage		±20	V	
I _D	Drain Current - Continuous	(Note 1a)	13	Λ	
	- Pulsed		50	— A	
P _D	Power Dissipation for Single Operation	(Note 1a)	3.0	W	
	Power Dissipation for Single Operation	(Note 1b)	1.2		
E _{AS}	Single Pulse Avalanche Energy	(Note 3)	181	mJ	
T _J , T _{STG}	Operating and Storage Junction Temperature Range		-55 to +150	°C	

Thermal Characteristics

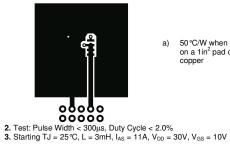
R _{eJA}	Thermal Resistance, Junction-to-Ambient	(Note 1a)	50	°C/W
R _{eJA}	Thermal Resistance, Junction-to-Ambient	(Note 1b)	125	°C/W
R _{eJC}	Thermal Resistance, Junction-to-Case	(Note 1)	25	°C/W

Package Marking and Ordering Information

Device Marking	Device	Reel Size	Tape width	Quantity
FDS6298	FDS6298	13"	12mm	2500 units

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Char	acteristics		•			•
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	30	-	-	V
<u>ΔBV_{DSS}</u> ΔT _J	Breakdown Voltage Temperature Coefficient	I_D = 250 μ A, Referenced to 25°C	-	30	-	mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 24 \text{ V}, V_{GS} = 0 \text{ V}$	-	,	1	μΑ
I _{GSS}	Gate-Body Leakage	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$	-	-	±100	nA
On Char	acteristics (Note 2)					
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250 \mu A$	1	1.7	3	V
$\Delta V_{GS(th)}$ ΔT_J	Gate Threshold Voltage Temperature Coefficient	I_D = 250 μ A, Referenced to 25°C	-	- 5	-	mV/°C
R _{DS(ON)}	Static Drain–Source On–Resistance	$\begin{split} V_{GS} &= 10 \text{ V, } I_D = 13 \text{ A} \\ V_{GS} &= 4.5 \text{ V, } I_D = 12 \text{ A} \\ V_{GS} &= 10 \text{ V, } I_D = 13 \text{ A, } T_J = 125 ^{\circ}\text{C} \end{split}$	-	7.4 9.4 11	9 12 15	mΩ
g _{FS}	Forward Transconductance	V _{DS} = 10 V, I _D = 13 A	-	58	-	S
Dynamic	Characteristics					
C _{iss}	Input Capacitance		-	1108	-	pF
Coss	Output Capacitance	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V},$	-	310	-	pF
Crss	Reverse Transfer Capacitance	f = 1.0 MHz	-	109	-	pF
R _G	Gate Resistance	$V_{GS} = 15 \text{ mV}, f = 1.0 \text{ MHz}$	0.3	1	1.7	Ω
Switchin	g Characteristics (Note 2)					
d(on)	Turn-On Delay Time		-	11	20	ns
r	Turn-On Rise Time	$V_{DD} = 15 \text{ V}, I_D = 1 \text{ A},$	-	5	10	ns
d(off)	Turn-Off Delay Time	$V_{GS} = 10 \text{ V}, R_{GEN} = 6 \Omega$	-	27	43	ns
.f	Turn-Off Fall Time		-	7	14	ns
Q_g	Total Gate Charge		-	10	14	nC
Q _{gs}	Gate-Source Charge	$V_{DS} = 15 \text{ V}, I_{D} = 13 \text{ A},$ $V_{GS} = 5 \text{ V}$	-	3	-	nC
Q_{gd}	Gate-Drain Charge	VGS – J V	-	3	-	nC
Drain–So	ource Diode Characteristics					
V _{SD}	Drain–Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = 2.1 \text{ A}$ (Note 2)	-	0.74	1.2	V
t _{rr}	Diode Reverse Recovery Time	$I_F = 13 \text{ A}, dI_F/dt = 100 \text{ A/}\mu\text{s}$	-	27	-	ns
Q _{rr}	Diode Reverse Recovery Charge		-	13	-	nC

1. R_{BJA} is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R_{BJC} is guaranteed by design while R_{BCA} is determined by the user's board design.



50 °C/W when mounted on a 1in² pad of 2 oz copper



- b) 125°C/W when mounted on a minimum pad.
- Scale 1:1 on letter size paper

Typical Characteristics

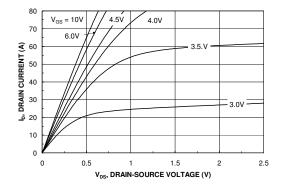
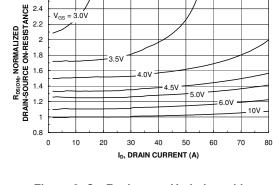


Figure 1. On-Region Characteristics.



2.6

Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

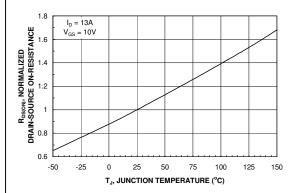


Figure 3. On-Resistance Variation with Temperature.

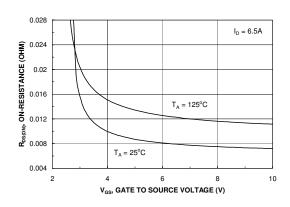


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

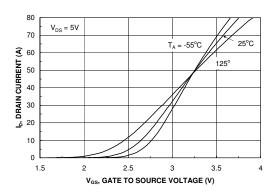


Figure 5. Transfer Characteristics.

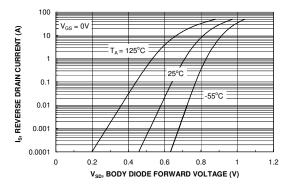
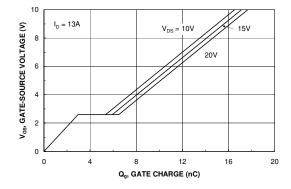


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

Typical Characteristics



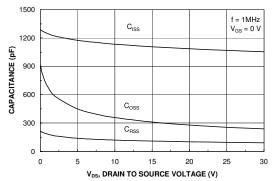
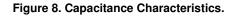
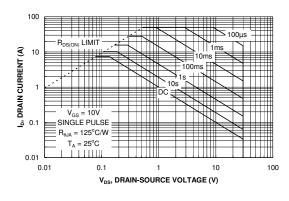


Figure 7. Gate Charge Characteristics.





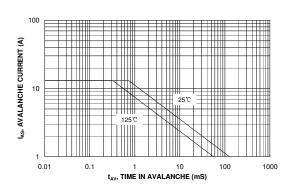


Figure 9. Maximum Safe Operating Area.

Figure 10. Unclamped Inductive Switching Capability

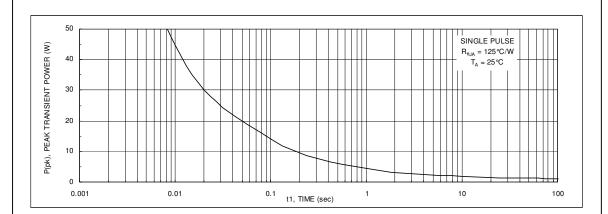


Figure 11. Single Pulse Maximum Power Dissipation.

Typical Characteristics

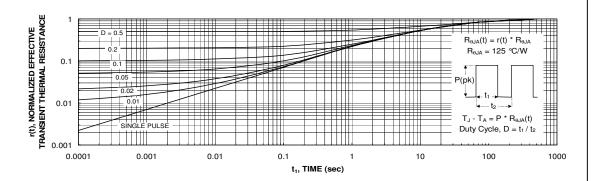


Figure 12. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1c. Transient thermal response will change depending on the circuit board design.

ON Semiconductor and in are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hol

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com N. American Technical Support: 800-282-9855 Toll Free USA/Canada Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910

Phone: 421 33 790 2910

Japan Customer Focus Center
Phone: 81–3–5817–1050

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative